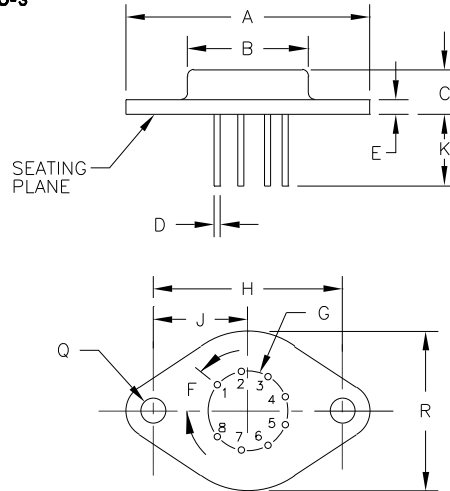


Package Number 030 - 8-Pin Metal TO-3



DIM	INCHES		MILLIMETERS		NOTE	DIM	INCHES		MILLIMETERS		NOTE
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	1.510	1.550	38.35	39.37							
B	.745	.770	18.92	19.56							
C	.260	.300	6.60	7.62							
D	.038	.042	0.97	1.07							
E	.080	.105	2.03	2.67							
F	40°	BASIC	40°	BASIC							
G	.500	BASIC	12.70	BASIC							
H	1.182	1.192	30.02	30.28							
J	.591	.596	15.01	15.14							
K	.400	.500	10.16	12.70							
Q	.151	.161	3.84	4.09							
R	.980	1.020	24.89	25.91							

NOTES:

- LEADS IN TRUE POSITION WITHIN .010" (.25mm) @ MMC AT SEATING PLANE.
- PIN NUMBERS SHOWN FOR REFERENCE ONLY. NUMBERS MAY NOT BE MARKED ON PACKAGE.

PACKAGE NUMBER: ZZ030 REV.: C
 JEDEC NUMBER: UNKNOWN



PACKAGE DRAWING

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